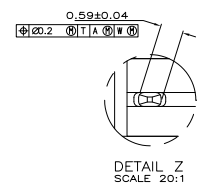
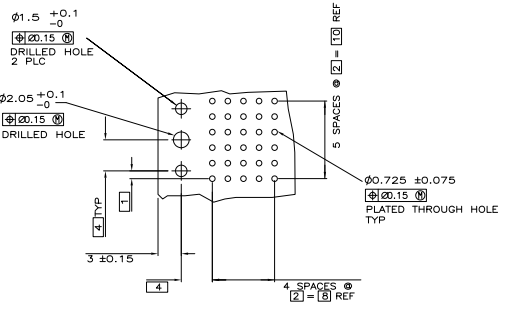
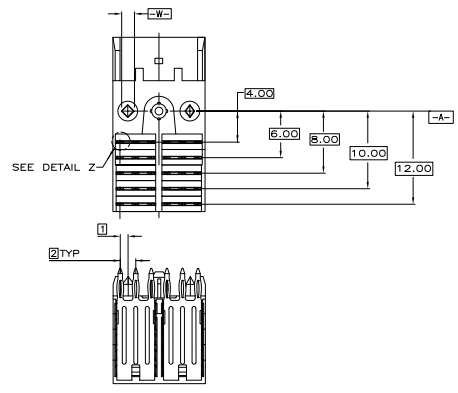
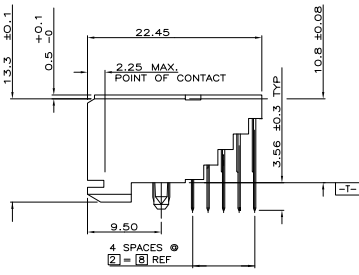
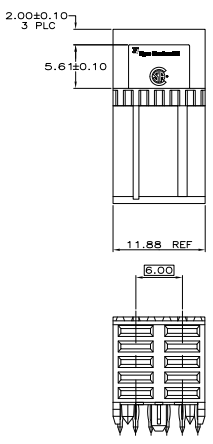


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REV	DATE	DESCRIPTION	BY	CHK	APP
AD	00				
J1		REVISED PER ECO-08-009182	22APR08	DH	AS

△ HOUSINGS MATERIAL: LIQUID CRYSTAL POLYMER.  
 △ CONTACT MATERIAL: COPPER ALLOY  
 △ CONTACT FINISH:  
 UNDERPLATE (ENTIRE CONTACT):  
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290  
 ON MATING SURFACES:  
 FLASH GOLD PER ASTM B 488, OVER  
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR  
 0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.  
 ON LEADS:  
 0.00127 MIN TIN-LEAD OVER UNDERPLATE.  
 LUBRICATION (MIN MATING SURFACES):  
 SURFACE CONDITIONER AFTER PLATING.



DETAIL Z  
 SCALE 20:1

RECOMMENDED CIRCUIT PATTERN  
 PER IPC-D300 TYPE II, CLASS C  
 (COMPONENT SIDE)

FINISH	NO OF POSN	PART NUMBER
		536649-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		BY: SHEFFY	DATE: 2-18-08	YTS Electronics Corporation
DRAWN BY: MELLUMES		DATE: 2-18-08	Harrisburg, PA 17105-3608	
CHECKED BY: MELLUMES		DATE: 2-18-08	ASSEMBLY, RECEPTACLE, 5 ROW, POWER MODULE,	
APPROVED BY: MELLUMES		DATE: 2-18-08	PRESS FIT LEAD, 3.56mm LEAD LENGTH,	
DATE: 2-18-08		DRAWING NO: A100779	REV: 0	REVISED TO: 2-PACK, 2mm FB
CUSTOMER DRAWING		DATE: 4-1	REV: 1	BY: J1